

(19)  
(12)

(KR)  
(A)

(51) 。 Int. Cl. <sup>7</sup> H05B 33/10		(11) (43)	10-2004-0037889 2004 05 08
(21)	10-2002-0066568		
(22)	2002 10 30		
(71)		575	
(72)		1043-8301	
		105 504	
(74)			
	:		
(54)			

.

1 ;

2 ;

3 ;

4 / ;

5 ;

.

2e

OELED,

1

2a

 $2e$ 

( )

300;                      310;

311;                      313;

315;                      320;

330; 331, 335;

341, 345; 350;

351, 355;            361;

365;                      370;

367, 375;            380;

390;            400;

A; TFT    B;

가, (Flat Panel Display) (OELD : Organic Electro Luminescence Display) (Contrast)

(OELD) , - (Carri  
er)

LD) , PMOELD(Passive Matrix OELD) AMOELD(Active Matrix OE

1

(AMOLED)

1

(100)

(110, buffer layer)

(110)

1

(120)

(130)

(130) , 2 (100)  
 (130) (140) (140) (121)  
 (125) (121) (125) (123)  
 50) (121) (125) (100) (121) (125)  
 , 3 (151, 155) (150)  
 (151, 155) (150) , 4  
 (151) (121) (161) (155) (125)  
 (165)  
 (161) (165) (100) (170) , 5  
 (161) (165) , (165)  
 (175)  
 ITO (175) (170) ITO , 6  
 (175) (165) (180)  
 (180) (100) (190) , 7  
 (180) (195)  
 (195) (180) (200) (200)  
 (210)  
 7 가 ,  
 , ITO  
 /

, 1  
 ;  
 ; 2  
 ;  
 ; 3  
 4 /  
 ; 5  
 ;  
 , / , /  
 , /  
 가  
 가 ,  
 Mo, MoW, Cr, Al, Al

,  
 2a 2e  
 2a , (300) TFT (A) (310) , 1 (300)  
 (310) (300) 가 (320) (300)  
 , (310) (320)  
 , SPC(Solid Phase Crystallization) ELA(Eximer Laser Annealing)  
 , (320) SiO<sub>2</sub>  
 2b , (320)  
 (310) , 2 TFT (A)  
 (330) (320) (331) (341)  
 (345) (B) (335) (335)  
 ITO IZO  
 가 , Mo, MoW, Cr, Al, Al  
 (330) (335)  
 ,  
 ,  
 , (310) (330)  
 (311) (315) (311) (315)  
 (313)  
 2c , (300) SiO<sub>2</sub> SiN<sub>x</sub>/SiO<sub>2</sub>  
 (350) (350) 3 (311)  
 (315) (351, 355) (B) (335)  
 (345) (350) 2000~10000  
 / , (3)  
 50)  
 2d , (300) (370)  
 , 4 , (370) (370)  
 (315) (351) (311) (361) (35)  
 5) (335) (365)  
 , (B) (335) (345)  
 (335) (367)  
 2c , (B) (350) (345)  
 2d (B) (335) (365) (345) (335) (365)  
 (335)  
 2e , (361) (365) (300) (Acryl)  
 (380) 5 (B) (380) (335)  
 (385)  
 (385) (335) (390) (300)  
 (400)

ITO , ITO (Redundancy) , ITO

(57)

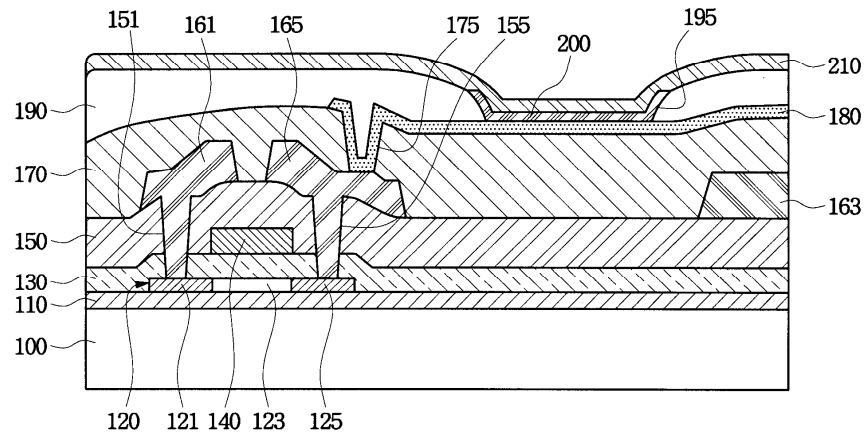
1. 1 ; ; ;
2. 2 ; ; ;
3. 3 ; ; ;
4. 4 / ; / ;
5. 5 ; ;

2. 1 , / , / .

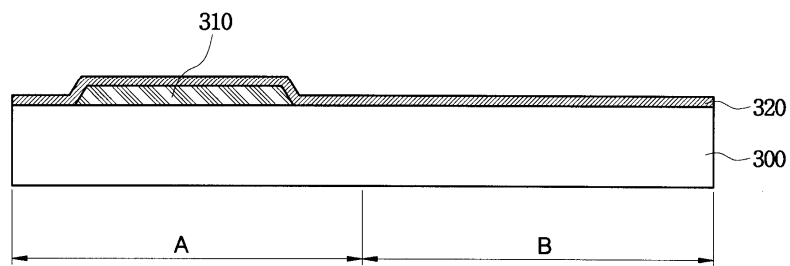
3. 1 , / 가 .

4. 1 , 가 , Mo, MoW, Cr, Al, Al

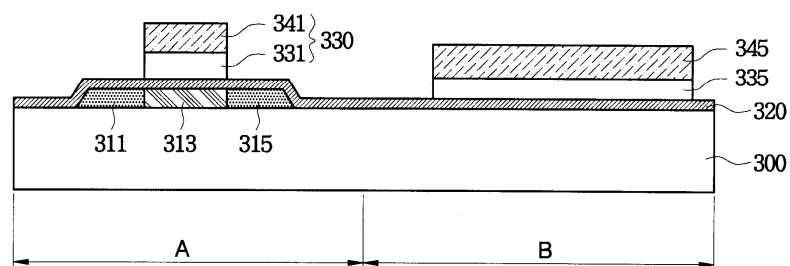
1



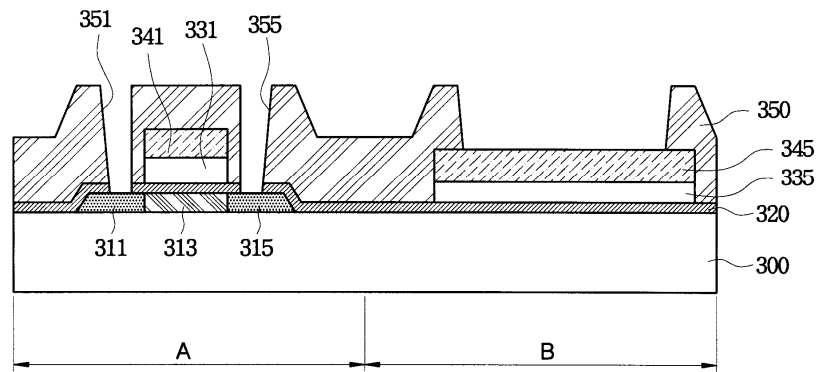
2a



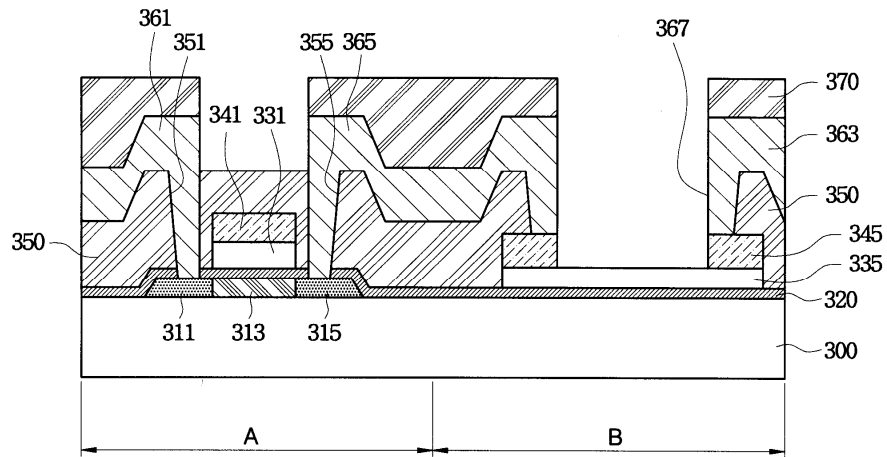
2b



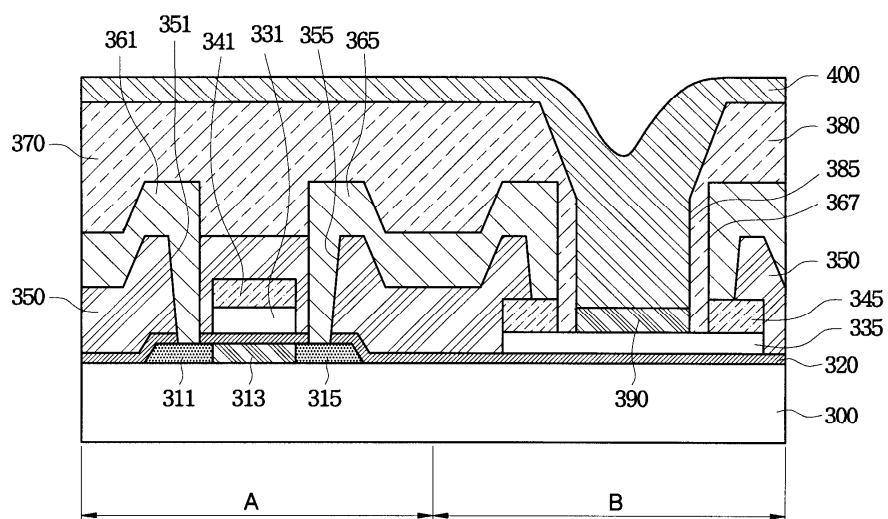
2c



2d



2e



This cross-sectional view shows a semiconductor device with a substrate 300. A trench 390 is formed in the substrate, with a bottom layer 320 and a side layer 335. The trench is filled with a material 345, and a layer 350 is formed on top of the trench. The trench is divided into two regions, A and B, by a vertical line. The trench is filled with a material 345, and a layer 350 is formed on top of the trench. The trench is divided into two regions, A and B, by a vertical line.